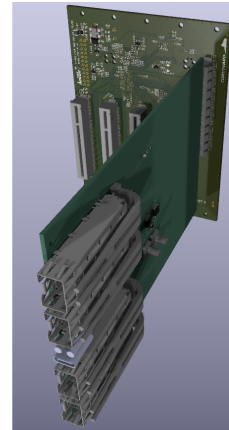


## F-HEC-COR

### HotRIO Eurocard Controller board

- HotRIO controller board solution for Eurocard-mounted systems.
- HotRIO-node capable hardware.
- Features 4 SFP communication interfaces.
- Backplane with 4 slots for expansion boards.



The HotRIO F-HEC-COR (codename Corcovado) is a set of two boards working together: Corcovado Backplane and Corcovado SFP. It is a HotRIO controller board developed by Fusion for Energy (F4E), that acts as a backplane with 4 slots for expansion boards, and with 4 SFPs for communication.

Its size allows 4 Corcovados to be installed on a standard 3U 84HP (19in) Eurocard chassis.

At its core, the F-HEC-COR board features a Lattice ECP5 FPGA, which handles all HotRIO protocol communication, manages expansion boards when connected, and performs the necessary signal acquisition and processing. To enable high-speed connectivity, the board includes four 1Gbps SFP fiber optic ports, allowing it to interface with other HotRIO nodes, general-purpose network equipment, or custom communication protocols using standard fiber optic cabling.

Because the board relies solely on high-speed fiber optic communication interfaces, aside from its expansion board connection, it is specifically designed as a communication node. This makes it an ideal solution not only for HotRIO systems but also for external applications requiring high-bandwidth fiber optic data transmission at speeds of up to 1Gbps. For use cases that involve low-speed or non-serialized fiber optic signals, it is recommended to use dedicated fiber optic I/O expansion boards.

### Technical Specifications

Form factor	Backplane: 99.075 x 129.6mm board, SFP board: 160 x 100mm Eurocard board
FPGA	LFE5UM5G-85F
Slots	4 Expansion board slots
Expansion board slot interface	16 x LVDS pairs (8 bidirectional, 8 Rx only), CAN bus, common SYNC and RESET outputs, individual INT input, generic A,B,C signals
Communication interfaces	4 x SFP modules (up to 1 Gbps each)
Clock inputs	50 MHz internal oscillator, 10 MHz external clock via SMB
Time sync	1 x external PPS signal via SMB
Power supply	24 V DC, 2.5A max, through 24-pin flat cable IDC connector

This board is designed to be used in each HotRIO Eurocard chassis, serving as the chassis master or controller. The mounting solution is optimized to leverage the FPGA on the Corcovado backplane as the main processor of the chassis, handling I/O operations, computation, and communication via the HotRIO protocol, as well as other supported protocols. In this architecture, the Corcovado board forms the core of the Eurocard chassis solution.



**Warning:** This document exclusively describes the hardware detailed herein. Any reference to software or firmware used to operate this hardware is outside the scope of this document.

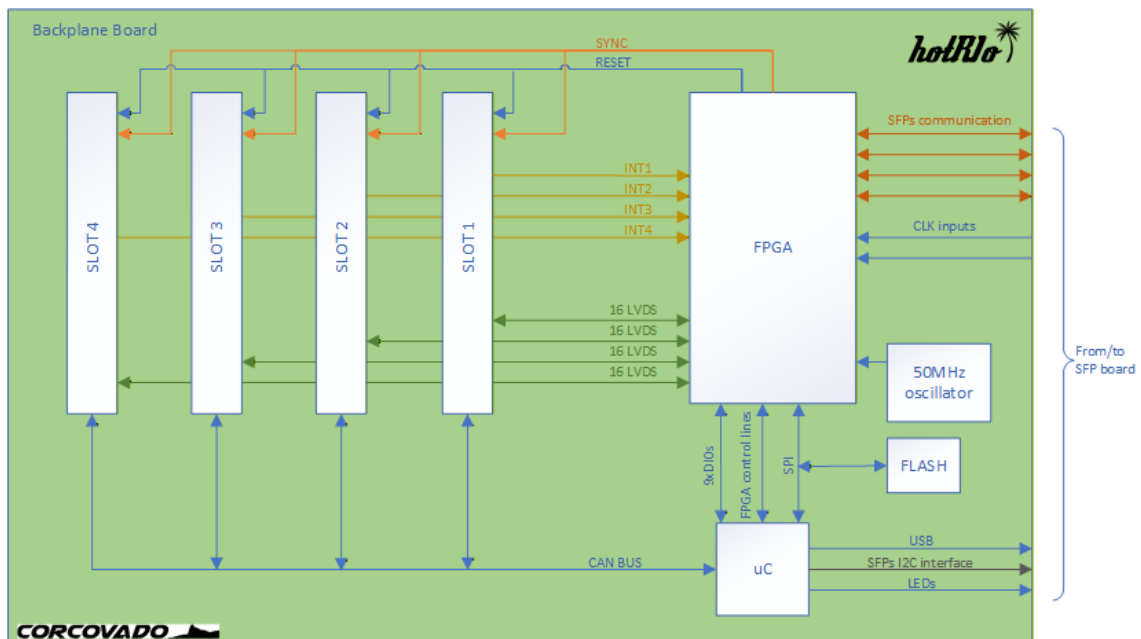
Developers are advised to consult separate documentation for any information related to software or firmware functionality.

# 1 Detailed description

## 1.1 Board Overview

The F-HEC-COR is a high-performance HotRIO Eurocard controller board developed by Fusion For Energy, purpose-built to deliver robust HotRIO communication and advanced local data processing capabilities within Eurocard chassis systems. At its core is a Lattice ECP5 FPGA, which interfaces directly with four SFP cages, each supporting SFP modules capable of data rates up to 1Gbps. This architecture enables the board to simultaneously manage high-speed fiber optic communication across multiple channels, supporting a wide range of protocols—including the HotRIO protocol and other custom or standard network protocols as required by the application.

The FPGA orchestrates the seamless transfer of data between the Eurocard backplane I/O and the SFP ports, ensuring efficient, low-latency communication for both control and data acquisition tasks. This makes the F-HEC-COR an ideal solution for applications demanding high bandwidth, flexible connectivity, and real-time processing within modular Eurocard-based systems.



## 1.2 FPGA

The HotRIO F-HEC-COR board is equipped with a Lattice Semiconductor LFE5UM5G-85F FPGA, which serves as the central processing and communication hub for the board.

The FPGA interfaces directly with four SFP cages (numbered 1 through 4), each connected via dedicated LVDS TX and RX pairs to the FPGA's SERDES blocks. This configuration supports data rates up to 1Gbps per SFP, utilizing 8b/10b encoding for robust high-speed communication. These SFP interfaces enable the board to connect to other HotRIO nodes, network equipment, or custom fiber optic links.

In addition to the SFP interfaces, the FPGA is connected to two SMB coaxial connectors on the board. One provides an external clock input (nominally 10MHz), and the other supplies an external PPS (Pulse Per Second) signal for precise time synchronization. Both signals are routed through NB3L553DG clock fanout buffers to ensure signal integrity before reaching the FPGA. This setup allows multiple HotRIO boards to operate synchronously, sharing a common clock and timing reference.

For standalone or fallback operation, the board includes a 50MHz crystal oscillator directly connected to the FPGA. This oscillator ensures a stable and reliable clock source for the FPGA, supporting backup, recovery, and management operations even if external timing signals are unavailable.

The FPGA exposes 64 LVDS pairs (16 per slot), 32 of which are bidirectional and the other 32 only RX, providing high-bandwidth, low-latency communication channels for interfacing with other boards and system components.

### 1.3 Manager microcontroller

The F-HEC-COR board integrates a STM32G0B1CE microcontroller, which serves as the board manager, handling essential management and supervisory functions. The main responsibilities of the manager microcontroller include:

- **FPGA firmware management and configuration:** The microcontroller oversees the loading and configuration of the FPGA firmware. It manages the SPI interface to the FPGA, orchestrating the transfer of the bitstream stored in external flash memory (MX25V20066) to the FPGA during boot. Additionally, the microcontroller can store and retrieve configuration files in the flash memory, enabling dynamic reconfiguration of the FPGA by writing to its internal registers via SPI.
- **CAN bus communication:** The microcontroller connects to the CAN bus available on the 4 slots of the backplane, facilitating communication with other board managers in the system. The microcontroller also coordinates management traffic, relays serial communications as needed, and verifies the presence and configuration of expansion boards to ensure compatibility with the intended FPGA firmware.
- **SFP module monitoring and diagnostics:** Through an I2C interface, the microcontroller monitors the SFP modules installed in the board's four cages. It detects module presence, reads diagnostic information, and accesses the internal memory map of each SFP to determine module type, operational parameters, and fault conditions.
- **System status reporting:** The microcontroller provides real-time status updates for the FPGA and other subsystems. It communicates status via serial interfaces (USB or sideband) and visually through 10 onboard serially-driven RGB LEDs, enabling users to quickly diagnose and debug board operation.

#### 1.3.1 External Memory and SPI Bus Architecture

The STM32G0B1CE manager microcontroller is paired with a MX25V20066 SPI flash memory, which stores both the FPGA firmware bitstream and a dedicated partition for microcontroller configuration files. The SPI bus is shared among the microcontroller, the FPGA, and the external flash memory, with bus mastership dynamically assigned based on the operational phase:

- **Normal operation:** The microcontroller acts as the SPI master, while the FPGA and flash memory function as slaves. This allows the microcontroller to access the FPGA's register map and manage the contents of the external flash.
- **FPGA boot sequence:** During FPGA configuration, the FPGA temporarily assumes the SPI master role to directly access the flash memory and load its bitstream. The microcontroller tri-states its SPI lines during this phase to avoid bus contention. Once configuration is complete, mastership reverts to the microcontroller. This flexible SPI architecture ensures reliable firmware loading, robust configuration management, and seamless coordination between the microcontroller and FPGA throughout all operational states.

#### 1.3.2 SFPs and I2C Bus Architecture

The F-HEC-COR board is equipped with four SFP cages, each capable of accepting standard SFP networking modules that interface directly with the FPGA for high-speed data transmission. In addition to the high-speed data lines, each SFP module provides a low-speed I2C interface, which is accessible by the manager microcontroller for monitoring and

configuration purposes. This I2C interface allows the microcontroller to read diagnostic information, configure operational parameters, and monitor the status of each SFP module, which is essential for system management and troubleshooting.

According to the SFF-8472 standard, each SFP module implements two fixed I2C device addresses: 0xA0 and 0xA2. The 0xA0 address is used for accessing the module's serial EEPROM, which contains identification, vendor, and configuration data. The 0xA2 address is reserved for accessing diagnostic monitoring interface (DMI) data, such as temperature, voltage, bias current, and optical power levels. Since these addresses are fixed and identical for all SFP modules, connecting multiple SFPs to the same I2C bus would result in address conflicts.

To resolve this, the F-HEC-COR board incorporates a TCA9548 I2C switch IC. The TCA9548 is an 8-channel I2C multiplexer that allows the microcontroller to select which SFP module is connected to the I2C bus at any given time. The microcontroller communicates with the TCA9548 at its unique I2C address and configures it to enable one of its downstream channels, thereby connecting the I2C bus to a specific SFP module. This approach ensures that, despite all SFP modules sharing the same internal I2C addresses, only one module is accessible on the bus at a time, preventing address collisions and enabling reliable communication.

In operation, the microcontroller sequentially selects each SFP channel via the TCA9548, performs the required read or write operations at addresses 0xA0 and 0xA2, and then moves to the next module as needed. This architecture provides robust and scalable management of multiple SFP modules, supporting advanced diagnostics and configuration capabilities for each port independently.

### 1.3.3 USB Connection

The manager microcontroller is equipped with a standard USB Type-C receptacle located on the front panel of the board. This USB interface connects directly to the manager microcontroller and provides management access via a serial command-line interface (CLI), which is exposed as a USB-CDC virtual serial port. The USB connection is intended exclusively for board management, configuration, and diagnostics; it is not designed for high-speed data transfer or application-level communication.

It is important to note that the USB interface is not connected to the FPGA and therefore cannot be used for direct FPGA programming or high-bandwidth data streaming. The USB port is compliant with the USB 2.0 standard, supporting only Full-Speed (12 Mbps) operation. As such, it is suitable for tasks such as firmware updates, board configuration, status monitoring, and diagnostic access, but not for high-speed data acquisition or real-time communication with the FPGA.

### 1.3.4 Light Indicators

The F-HEC-COR board is equipped with a total of 10 addressable RGB LEDs, all controlled by the manager microcontroller via a serial interface. These LEDs provide clear, real-time visual feedback on the operational status of the board and its subsystems. Specifically, each SFP module is associated with two dedicated LEDs, enabling per-port status indication such as link activity, fault conditions, or module presence. The remaining two LEDs are reserved for displaying the overall board status, including power, initialization, or error states. This flexible LED arrangement allows users and technicians to quickly assess board health and activity at a glance, streamlining diagnostics and system monitoring.

### 1.3.5 CAN Bus

The F-HEC-COR board is equipped with CAN bus capabilities to facilitate communication between all boards connected to the Eurocard backplane. The board's manager microcontroller coordinates management traffic and communicates with expansion boards.

The microcontroller supports both CAN 2.0 and Flexible Data-rate CAN (FD-CAN), with data rates up to 8 Mbit/s during the data phase.

The backplane is equipped with CAN transceivers featuring enable/disable (isolation) capabilities. This allows the controller board installed in the master slot to selectively enable or disable CAN connectivity for each slot. Such control is leveraged for several advanced features:

- **Software updates:** The master board can isolate and update the firmware of expansion board manager microcontrollers over the CAN bus, ensuring reliable and targeted updates.

- **Slot-based addressing:** During system initialization, the master assigns a unique CAN base address to each expansion board based on its physical slot location, enabling automatic board indexing and streamlined communication.
- **Bus arbitration and diagnostics:** By selectively enabling CAN transceivers, the master can perform diagnostics, isolate faulty boards, and manage bus arbitration to maintain system reliability.

## 2 Interfaces

This section provides an overview of the main interfaces available on the F-HEC-COR board. Each interface is briefly described, including its function and intended use. For most interfaces, a mechanical diagram is provided to indicate their physical location on the board.

**SFP Cages (4x):** The board features four SFP (Small Form-factor Pluggable) cages, each supporting standard SFP modules for high-speed fiber optic communication. These interfaces are directly connected to the FPGA, enabling data rates up to 1 Gbps per port. The SFP cages are located along the front edge of the board for easy access and hot-swapping. Each SFP port also provides a low-speed I2C interface for module monitoring and diagnostics, managed by the onboard microcontroller.

**SMB Coaxial Connectors (2x):** Two SMB coaxial connectors are provided for external timing and synchronization signals:

- **Clock Input:** Accepts an external reference clock (nominally 10 MHz) for precise timing.
- **PPS Input:** Accepts an external Pulse Per Second (PPS) signal for time synchronization. Both signals are routed to the FPGA via clock fanout buffers. The signals need to be connected with pigtailed to the rightmost front panel of the chassis, which also holds the power connector.
- **Management USB Type-C:** A standard USB Type-C connector is available on the front panel, providing a management interface to the onboard microcontroller. This port is used for board configuration, firmware updates, diagnostics, and status monitoring via a USB-CDC virtual serial port. It is not intended for high-speed data transfer or direct FPGA programming.
- **PCIe Slots:** 4 98-pin PCIe x8 slots are available on the backplane for connecting expansion boards. Each slot features 16 LVDS pairs (8 bidirectional, 8 Rx only), CAN bus, common SYNC and RESET outputs, individual INT input, and 3 generic signals A, B and C. In summary, the F-HEC-COR board provides a comprehensive set of interfaces for high-speed communication, precise timing, system management, and robust integration within Eurocard-based systems. The mechanical diagrams above indicate the physical location of each interface, while the detailed pinout ensures correct system-level connectivity.



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